

APTB1612SURKQBDC-F01

1.6 x 1.25 mm Bi-Color SMD Chip LED Lamp

DESCRIPTIONS

- The Hyper Red source color devices are made with AlGaInP on GaAs substrate Light Emitting Diode
- The Blue source color devices are made with InGaN Light Emitting Diode
- · Electrostatic discharge and power surge could damage the LEDs
- It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs
- · All devices, equipments and machineries must be electrically grounded

FEATURES

- 1.6 mm x 1.25 mm SMD LED. 0.65 mm thickness
- · Bi-color, low power consumption
- · Wide viewing angle
- · Ideal for backlight and indicator
- Package: 2000 pcs / reel
- Moisture sensitivity level: 3
- RoHS compliant

APPLICATIONS

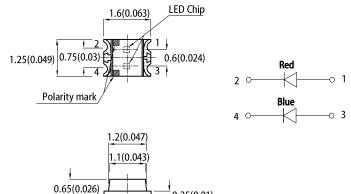
- Backlight
- · Status indicator
- Home and smart appliances
- · Wearable and portable devices
- · Healthcare applications

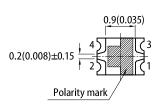
ATTENTION

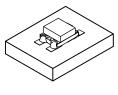
Observe precautions for handling electrostatic discharge sensitive devices



PACKAGE DIMENSIONS

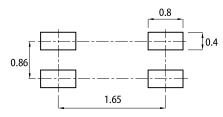






RECOMMENDED SOLDERING PATTERN

(units: mm; tolerance: ± 0.1)



- 1. All dimensions are in millimeters (inches)
- Tolerance is ±0.2(0.008") unless otherwise noted.
 The specifications, characteristics and technical data described in the datasheet are subject to
- change without prior notice.

 The device has a single mounting surface. The device must be mounted according to the specifications.

SELECTION GUIDE

Part Number	Emitting Color (Material)	Lens Type	Iv (mcd) @ 20mA [2]		Viewing Angle [1]	
			Min.	Тур.	201/2	
APTB1612SURKQBDC-F01	■ Hyper Red (AlGaInP)	- Water Clear	120	200		
			*40	*80	150°	
	■ Blue (InGaN)		40	80		
			*40	*80		

1. 91/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value 2. Luminous intensity / luminous flux: +/-15%.

Luminous intensity value is traceable to CIE127-2007 standards.





ELECTRICAL / OPTICAL CHARACTERISTICS at T_A=25°C

Parameter	Symbol	Emitting Color	Value		Unit
			Тур.	Max.	
Wavelength at Peak Emission I _F = 20mA	λ_{peak}	Hyper Red Blue	645 460	-	nm
Dominant Wavelength I _F = 20mA	λ _{dom} ^[1]	Hyper Red Blue	630 465	-	nm
Spectral Bandwidth at 50% Φ REL MAX I _F = 20mA	Δλ	Hyper Red Blue	28 25	-	nm
Capacitance	С	Hyper Red Blue	35 100	-	pF
Forward Voltage I _F = 20mA	V _F ^[2]	Hyper Red Blue	1.95 3.3	2.5 4.0	V
Reverse Current (V _R = 5V)	I _R	Hyper Red Blue	-	10 50	μА

Notes:

ABSOLUTE MAXIMUM RATINGS at $T_A=25$ °C

Parameter	Symbol	Value	Unit	
1 3 3 3 3 3		Hyper Red	Blue	
Power Dissipation	P _D	75	120	mW
Reverse Voltage	V _R	5	5	V
Junction Temperature	TJ	115	115	°C
Operating Temperature	T _{op}	-40 To +8	°C	
Storage Temperature	T _{stg}	-40 To +85		°C
DC Forward Current	I _F	30	30	mA
Peak Forward Current	I _{FM} ^[1]	185	150	mA
Electrostatic Discharge Threshold (HBM)	-	3000	250	V

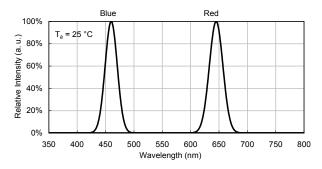
^{1.} The dominant wavelength (λd) above is the setup value of the sorting machine. (Tolerance λd:±1nm.)
2. Forward voltage: ±0.1V.
3. Wavelength value is traceable to CIE127-2007 standards.
4. Excess driving current and / or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

Notes:
1. 1/10 Duty Cycle, 0.1ms Pulse Width.
2. Relative humidity levels maintained between 40% and 60% in production area are recommended to avoid the build-up of static electricity – Ref JEDEC/JESD625-A and JEDEC/J-STD-033.

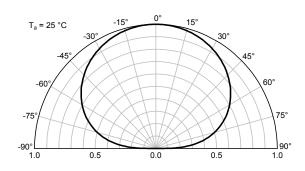


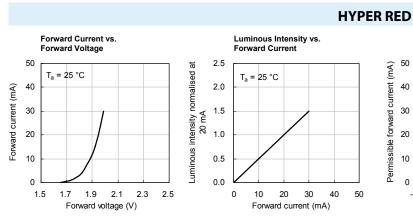
TECHNICAL DATA

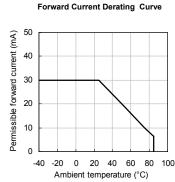
RELATIVE INTENSITY vs. WAVELENGTH

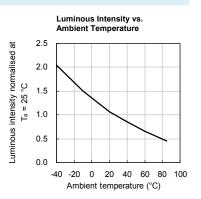


SPATIAL DISTRIBUTION

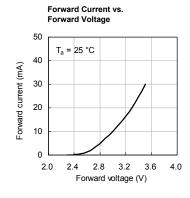


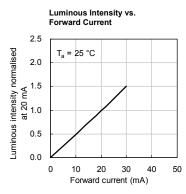


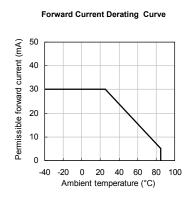


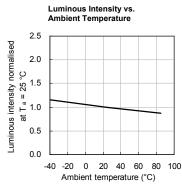


BLUE











REFLOW SOLDERING PROFILE for LEAD-FREE SMD PROCESS

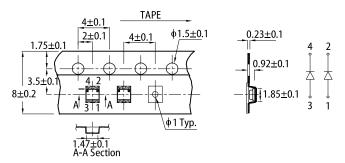
300 above 255°C (°C) 260°C max. 30s max. 10s max. 250 3°C/s max. 6°C/s max. 200 150 Temperature pre-heating 100 150~200°C above 217°C 60~120s 60~150s 50 -25°C 0 50 100 150 200 250 300 (sec) Time

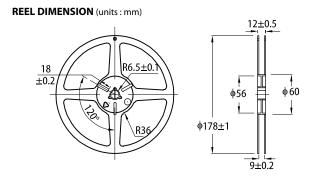
- 1. Don't cause stress to the LEDs while it is exposed to high temperature.

 2. The maximum number of reflow soldering passes is 2 times.

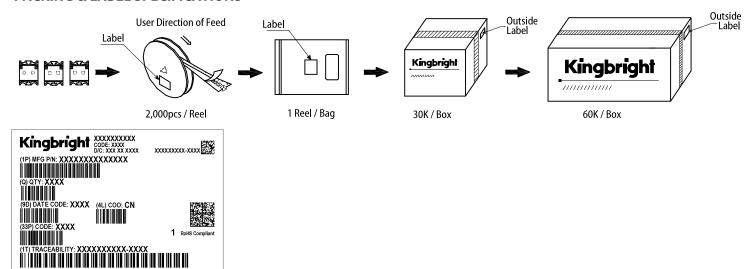
 3. Reflow soldering is recommended. Other soldering methods are not recommended as they might

TAPE SPECIFICATIONS (units:mm)





PACKING & LABEL SPECIFICATIONS



PRECAUTIONARY NOTES

- The information included in this document reflects representative usage scenarios and is intended for technical reference only.
- The part number, type, and specifications mentioned in this document are subject to future change and improvement without notice. Before production usage customer should refer to the latest datasheet for the updated specifications.
- When using the products referenced in this document, please make sure the product is being operated within the environmental and electrical limits specified in the datasheet. If customer usage exceeds the specified limits, Kingbright will not be responsible for any subsequent issues.

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